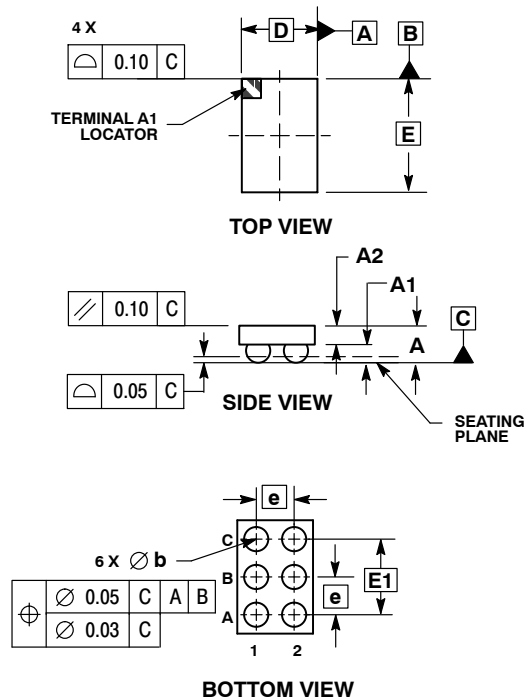



A1
SCALE 4:1

6 PIN FLIP-CHIP
CASE 499AH
ISSUE O

DATE 19 APR 2004



NOTES:

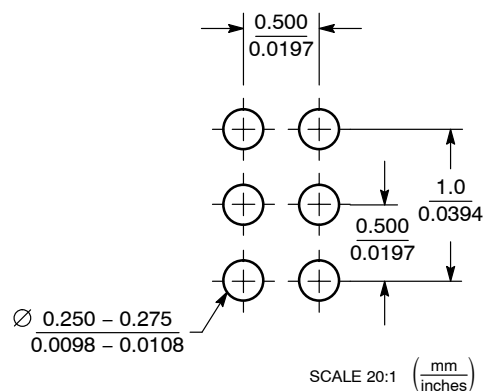
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	0.448	0.533
A1	0.210	0.270
A2	0.238	0.263
D	1.000	BSC
E	1.50	BSC
b	0.290	0.340
e	0.500	BSC
E1	1.000	BSC

GENERIC
MARKING DIAGRAM*


XXX = Specific Device Code
 A = Assembly Location
 L = Wafer Lot
 Y = Year
 W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

SOLDERING FOOTPRINT*


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	6 PIN FLIP-CHIP, NCP400, 1.00 X 1.5 MM, 0.50 MM PITCH	PAGE 1 OF 1

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